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PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of: Agarwal et al.

Application No. 09/590,795

Filed: June 8, 2000

For: METHODS FOR FORMING AND
INTEGRATED CIRCUIT STRUCTURES
CONTAINING RUTHENIUM AND TUNGSTEN
CONTAINING LAYERS

Examiner: Cuong Q. Nguyen

Date: May 13, 2002

Art Unit: 2811



CERTIFICATE OF MAILING

I hereby certify that this paper and the documents referred to as being attached or enclosed herewith are being deposited with the United States Postal Service on May 13, 2002 as First Class Mail in an envelope addressed to: COMMISSIONER FOR PATENTS, WASHINGTON, D.C. 20231.

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Attorney for Applicant

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INFORMATION DISCLOSURE STATEMENT PURSUANT TO
37 C.F.R. § 1.97(c)

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Listed on the accompanying form PTO-1449 and enclosed herewith are several English-language and/or non-English-language documents. Applicants respectfully request that these documents be listed as references cited on the issued patent. This Information Disclosure Statement is being mailed before Applicants received a final action, a notice of allowance, or an action that otherwise closes prosecution in the referenced application.

The undersigned hereby certifies that the information submitted herewith was cited in an International Search Report in a counterpart PCT/EPC application on April 2, 2002, which was less than three months prior to the filing of this statement.

Submission of these documents is not an admission that these documents are prior art with respect to the subject application.

Please charge any fees required for Applicants to file this Information Disclosure Statement to Deposit Account No. 02-4550. A **duplicate** copy of this Information Disclosure Statement is enclosed.

Respectfully submitted,

KLARQUIST SPARKMAN, LLP

By



Michael D. Jones
Registration No. 41,879

One World Trade Center, Suite 1600
121 S.W. Salmon Street
Portland, Oregon 97204
Telephone: (503) 226-7391
Facsimile: (503) 228-9446